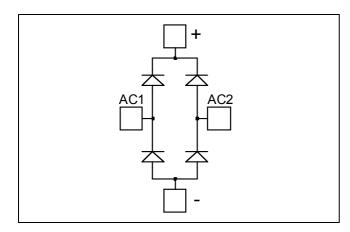


Diode Full Bridge Power Module

$$V_{RRM} = 600V$$

 $I_{C} = 200A$ @ $T_{C} = 80^{\circ}C$



Application

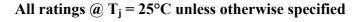
- Uninterruptible Power Supply (UPS)
- Induction heating
- Welding equipment
- High speed rectifiers

Features

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
- Very low stray inductance
 - Symmetrical design
 - M5 power connectors
- High level of integration



- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant



Absolute maximum ratings

Symbol	Parameter				Max ratings	Unit	
V_R	Maximum DC reverse Voltage				600	V	
V_{RRM}	Maximum Peak Repetitive Revers	e Voltage			000	V	
T	Maximum Average Forward	D. 4	500/	$T_C = 25^{\circ}C$	270	A	
$I_{F(AV)}$	Current	Duty cycle	e = 50%	$T_C = 80$ °C	200		
I _{F(RMS)}	RMS Forward Current	Duty cycle = 50%		$T_C = 45^{\circ}C$	270	Λ	
I_{FSM}	Non-Repetitive Forward Surge Cu	rrent 8.3ms		$T_C = 45^{\circ}C$	1500		

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

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Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
V_{F}	Diode Forward Voltage	$I_F = 200A$			1.6	2.0	V
		$I_F = 400A$			2.0		
		$I_F = 200A$	$T_{j} = 125^{\circ}C$		1.3		
I_{RM}	Maximum Reverse Leakage Current	$V_{\rm p} = 600 {\rm V}$	$T_i = 25^{\circ}C$			350	4
			$T_j = 125$ °C			600	μΑ
C_{T}	Junction Capacitance	$V_R = 600V$			380		pF

Dynamic Characteristics

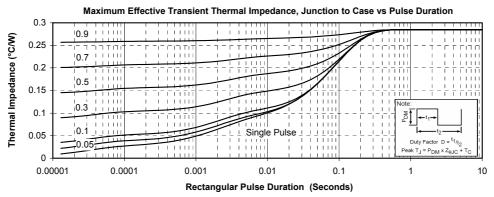
Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
t_{rr}	Reverse Recovery Time	$I_F=1A, V_R=30V$ $di/dt = 200A/\mu s$	$T_j = 25^{\circ}C$		34		ns
t _{rr}	Reverse Recovery Time		$T_j = 25^{\circ}C$		160		- ns
			$T_j = 125$ °C		220		
Q _{rr}	Reverse Recovery Charge	$I_F = 200A$ $V_R = 400V$	$T_j = 25^{\circ}C$		580		nC
Qrr	Reverse Recovery Charge	$di/dt = 400 \text{ A/} \mu \text{s}$	$T_j = 125$ °C		3060		iiC
I_{RRM}	Reverse Recovery Current		$T_j = 25$ °C		10		A
	Reverse Recovery Current		$T_{j} = 125^{\circ}C$		26		Λ.
t_{rr}	Reverse Recovery Time	$I_F = 200A$ $V_R = 400V$ $di/dt = 2000A/\mu s$			100		ns
Qrr	Reverse Recovery Charge		$T_j = 125$ °C		5.78		μС
I_{RRM}	Reverse Recovery Current				88		A

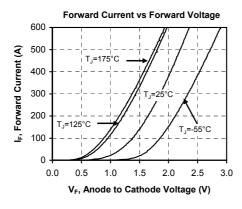
Thermal and package characteristics

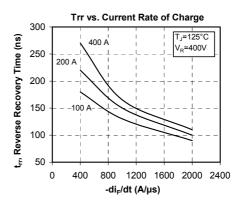
Symbol	Characteristic			Min	Typ	Max	Unit
R_{thJC}	Junction to Case Thermal Resistance					0.285	°C/W
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V
T_{J}	Operating junction temperature range			-40		175	
T_{STG}	Storage Temperature Range			-40		125	°C
$T_{\rm C}$	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M6	3		5	N.m
		For terminals	M5	2		3.5	11.111
Wt	Package Weight					300	g

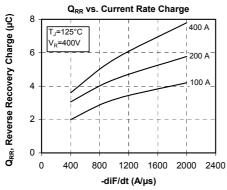


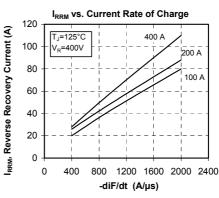
Typical Performance Curve

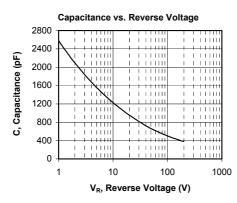


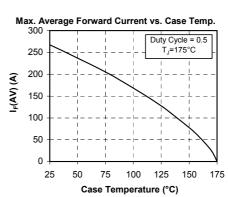








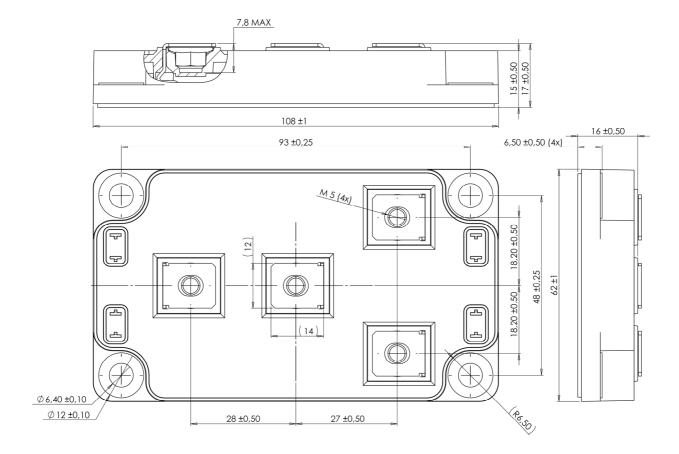




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SP6 Package outline (dimensions in mm)





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